# TEST PRODUCT QUALIFICATION REPORT

## TITLE:

ADSP-2147x 196-Ball CSP\_BGA

Test Second Source UTAC (Singapore) Qualification

## **PCN NUMBER:**

23\_0254

# **REVISION:**

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## DATE:

20 November 2023

#### **PROJECT BACKGROUND**

Test correlation is carried out to qualify UTAC Singapore as an additional final test site for ADI devices to support production.

#### SUMMARY

All references to ADSP-2147x in this report, apply to all 196-Ball CSP\_BGA ADSP-21478/9 products.

ADSP-2147x is released at UTAC as 2nd source test solution.

There is no change to the form, fit, function, quality, or reliability between platforms.

This report documents the successful completion of the product test correlation requirements of ADSP-

2147x 196-Ball CSP\_BGA between STATS ChipPAC and UTAC sites.

Test product qualification was performed according to Analog Devices Specification

#### TEST AND PRODUCT INFORMATION

Device	ADSP-2147x
Package	196-Ball CSP_BGA, 12x12x1.41mm, 0.8mm pitch
Tester Platform	HP93K_6

#### **Description and Test Results**

Table 1 provides a description of the qualification tests conducted and corresponding test results for ADSP-2147x. All the units have undergone electrical tests on both the sending and receiving sites on the same test platform. Any device that did not meet the electrical qualification requirements without further analysis and data to prove passing, the qualification would be considered failed.

Table 1. Test i foddet fransfer Qaaineation efferia								
Generic	Package	Lot Size	Sending Site	Receiving Site	Mean Shift =< 5%	Sigma Ratio =< 1.3		
ADSP-2147x	196-Ball CSP_BGA, 12x12x1.41mm, 0.8mm pitch	100	SCS	UTAC	Passed	Passed		

Table 1. Test Product Transfer Qualification Criteria

The ADSP-2147x was qualified by running a qualification lot with 100 units both in STATS ChipPAC and UTAC. Data between sites were analyzed as summarized in Table 1.

A passing result was recorded when the yield from receiving site met or exceeded yield from sending site as summarized in Table 2. Succeeding lots with increased quantity will be closely monitored once the device

GENERIC	Package	Package Lot Size Test Site		Results					
ADSP-2147x	196-Ball CSP_BGA, 12x12x1.41mm, 0.8mm pitch	100	UTAC	Passed					

Table 2. Test Product Transfer Qualification Lot Run

No valid rejects were encountered during the said evaluation in both sending and receiving sites.

#### **Rejects Verifications**

5 valid rejects tested in STATS ChipPAC and UTAC having the same result.

Unit #	SCS	UTAC
1	Failed	Failed
2	Failed	Failed
3	Failed	Failed
4	Failed	Failed
5	Failed	Failed

Table 3. Setup verification using Reject units.

## ADSP-2147x Initial Process Study (Test Temperature = 130 degC)

	Datasheet Specs			Site (STATS-ChipPac Singapore)			Site (UTAC Singapore)					
Key Datasheet Parameter	Min	Nom	Max	Units	Mean	Stdv	Cpk	Mean	Stdv	Cpk	GR&R (%)	NDC
						-			-	_	_	_
SIDD			0.0548	А	0.007	0.000569	>10	0.009	0.000734	>10	2.84676	50
IIL			-10	uA	-0.003	0.001481	>10	-0.012	0.001481	>10	0.147	1918
ШН			10	uA	0.007	0.003333	>10	0.015	0.001481	>10	0.251	1126
IOZL			-10	uA	-0.002	0.002963	>10	-0.01	0.002222	>10	0.0872	3245
IOZH			10	uA	0.007	0.004074	>10	0.018	0.002222	>10	0.105	2702
VIL			0.8	V	1.155	0.003704	>10	1.16	0.003704	>10	9.096	11
VIH	2			V	1.27	0.003704	>10	1.275	0.003704	>10	2.909	61
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VOL			0.4	V	0.03	0.003704	>10	0.029	0.003704	>10	0.6212	228
VOH	2.4			V	3.105	0.002593	>10	3.095	0.001852	>10	0.1277	494